CRMJBL3407B

P-Channel -30V, 51mΩ Typ. Power MOSFET

Description

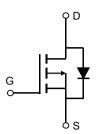
Features

• -30V, -3.8A

$$R_{DS(ON)}$$
 Typ = 51m Ω @ V_{GS} = -10 V

$$R_{DS(ON)}$$
 Typ = 76m Ω @ V_{GS} = -4.5V

- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead Free

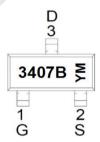


Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management





Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMJBL3407B	3407B	SOT-23-3L	TAPING	7"	3000	120000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		-30	V
V_{GS}	Gate-to-Source Voltage	±20	V	
	Continuous Drain Current	T _A = 25°C	-3.8	Α
l _D		T _A = 100°C	-2.28	Α
I_{DM}	Pulsed Drain Current (1)		-15.2	Α
P_{D}	Power Dissipation	T _A = 25°C	1.7	W
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient ⁽²⁾		73.5	°C/W
T_J,T_STG	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30V, V_{GS} = 0V$	-	-	-1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1	-1.5	-2	V
R _{DS(ON)} S	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = -10V, I_D = -3.8A$	-	51	66	mΩ
		$V_{GS} = -4.5V, I_D = -3A$	-	76	98	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-(260	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = -15V,$ f = 1MHz	X -	52	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 11011 12	-	41	-	pF
Q _g	Total Gate Charge		<u></u>	5.5	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } -10V$ $V_{DS} = -15V, I_{D} = -3A$	-	0.9	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} = -13V, I _D = -3A	-	1.3	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	10	-	ns
t _r	Turn-On Rise Time	$V_{GS} = -10V, V_{DD} = -15V$	-	54	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_D = -3A, R_{GEN} = 2.5 Ω	-	16	-	ns
t_{f}	Turn-Off Fall Time		-	8	-	ns
Drain-So	urce Diode Characteristics and M	lax Ratings				
I _S	Maximum Continuous Drain to Source Diode Forward Current			-	-3.8	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	-15.2	Α
V _{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = -3A$	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	1 000 17/11 4000	-	8	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = -3.8A$, di/dt = 100A/us	-	3	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

Test Circuit

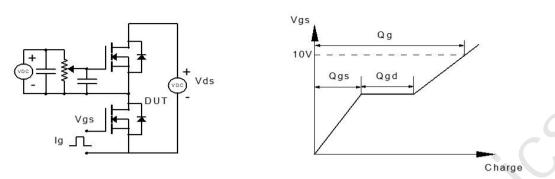


Figure 1: Gate Charge Test Circuit & Waveform

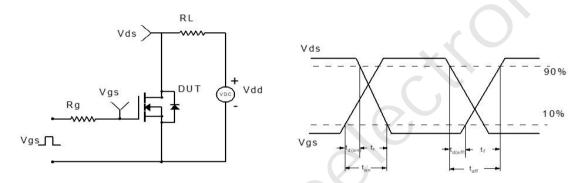


Figure 2: Resistive Switching Test Circuit & Waveform

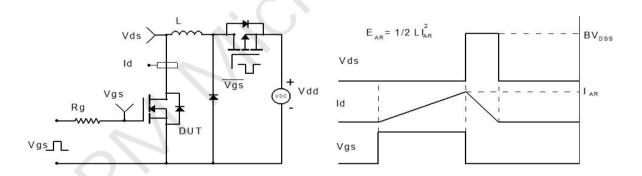


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

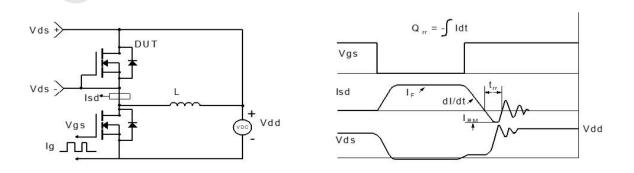
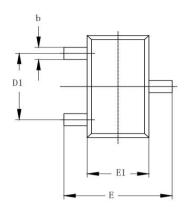


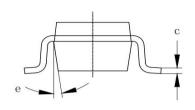
Figure 4: Diode Recovery Test Circuit & Waveform

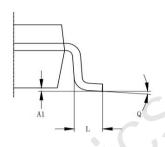


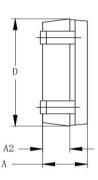
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Package Mechanical Data(SOT-23-3L)









	COMMON D	IMENSION (MM)			
PKG					
SYMBOL	MIN	TYP	MAX		
Α	1.080	1.100	1. 120		
A1	0. 010	0.060	0. 150		
A2	0, 640	0. 670	0. 700		
b	0. 325	0. 350	0. 375		
c	0. 125	0. 135	0. 150		
D	2. 920	2.930	2.980		
D1	1.875	1.900	1.925		
E	2. 650	2.800	2.950		
E1	1.580	1.600	1.670		
L	0. 300	0. 450	0.600		
e	8°				
Q	0°	4°	8°		

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Contact information

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